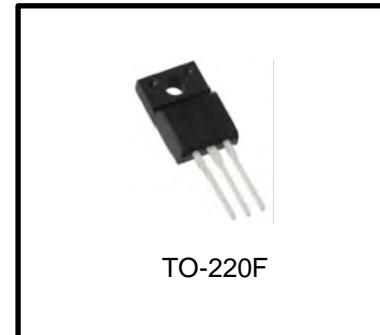


600V 0.06Ω Super Junction Power MOSFET

Description

WMOS™ C4 is Wayon's 4th generation super junction MOSFET family that is utilizing charge balance technology for extremely low on-resistance and low gate charge performance. WMOS™ C4 is suitable for applications which require superior power density and outstanding efficiency.

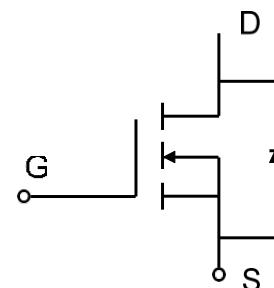


Features

- $V_{DS} = 650V @ T_{j,max}$
- Typ. $R_{DS(on)} = 0.06\Omega$
- 100% UIS tested
- Pb-free plating, Halogen free

Applications

LED Lighting, Charger, Adapter, PC, LCD TV, Server



Absolute Maximum Ratings

Parameter	Symbol	WMK/WMM/WMN/WMJ	WML	Unit
Drain-source voltage	V_{DSS}	600		V
Continuous drain current ¹⁾ ($T_C = 25^\circ C$)	I_D	50		A
($T_C = 100^\circ C$)		26		A
Pulsed drain current ²⁾	I_{DM}	90		A
Gate-source voltage	V_{GS}	± 30		V
Avalanche energy, single pulse ³⁾	E_{AS}	940		mJ
Avalanche energy, repetitive ²⁾	E_{AR}	1.3		mJ
Avalanche current, repetitive ²⁾	I_{AR}	5		A
Power dissipation ($T_C = 25^\circ C$)	P_D	350	34	W
-Derate above 25°C		2.8	0.27	W/°C
Operating and storage temperature range	T_j, T_{stg}	-55 to +150		°C
Continuous diode forward current ¹⁾	I_S	50		A
Diode pulse current ²⁾	$I_{S,pulse}$	90		A

Thermal Characteristics

Parameter	Symbol	WMK/WMM/WMN/WMJ	WML	Unit
Thermal resistance, junction-to-case	$R_{\theta JC}$	0.36	3.6	°C/W
Thermal resistance, junction-to-ambient	$R_{\theta A}$	62	80	°C/W



WMK53N60C4

Electrical Characteristics $T_c = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0 \text{ V}, I_{\text{D}}=1 \text{ mA}$	600	-	-	V
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=0.25 \text{ mA}$	2	3	4	V
Drain cut-off current	I_{DSS}	$V_{\text{DS}}=600 \text{ V}, V_{\text{GS}}=0 \text{ V},$ $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	-	-	1	μA
Gate leakage current, forward	I_{GSSF}	$V_{\text{GS}}=20 \text{ V}, V_{\text{DS}}=0 \text{ V}$	-	-	100	nA
Gate leakage current, reverse	I_{GSSR}	$V_{\text{GS}}=-20 \text{ V}, V_{\text{DS}}=0 \text{ V}$	-	-	-100	nA
Drain-source on-state resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=15 \text{ A}$ $T_j = 25^\circ\text{C}$	-	0.06	0.07	Ω
Dynamic characteristics						
Input capacitance	C_{iss}	$V_{\text{DS}}=100 \text{ V}, V_{\text{GS}}=0 \text{ V},$ $f = 1 \text{ MHz}$	-	3400	-	pF
Output capacitance	C_{oss}		-	115	-	
Reverse transfer capacitance	C_{rss}		-	2.7	-	
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=300 \text{ V}, I_{\text{D}}=15 \text{ A}$ $R_{\text{G}}=25 \Omega, V_{\text{GS}}=10 \text{ V}$	-	53	-	ns
Rise time	t_r		-	40	-	
Turn-off delay time	$t_{\text{d}(\text{off})}$		-	214	-	
Fall time	t_f		-	28	-	
Gate charge characteristics						
Gate to source charge	Q_{gs}	$V_{\text{DD}}=480 \text{ V}, I_{\text{D}}=15 \text{ A},$ $V_{\text{GS}}=0 \text{ to } 10 \text{ V}$	-	15.0	-	nC
Gate to drain charge	Q_{gd}		-	15.6	-	
Gate charge total	Q_g		-	58.0	-	
Gate plateau voltage	V_{plateau}		-	5.0	-	V
Reverse diode characteristics						
Diode forward voltage	V_{SD}	$V_{\text{GS}}=0 \text{ V}, I_{\text{F}}=15 \text{ A}$	-	-	1.2	V
Reverse recovery time	t_{rr}	$V_R=50 \text{ V}, I_{\text{F}}=15 \text{ A},$ $dI/dt=100 \text{ A}/\mu\text{s}$	-	280	-	ns
Reverse recovery charge	Q_{rr}		-	4.3	-	μC
Peak reverse recovery current	I_{rrm}		-	30	-	A

Notes:

1. Limited by T_j max. Maximum duty cycle D=0.5.
2. Pulse width limited by maximum junction temperature.
3. $I_{\text{AS}} = 5 \text{ A}, V_{\text{DD}} = 50 \text{ V}, R_{\text{G}} = 25 \Omega$, starting $T_j = 25^\circ\text{C}$.

Typical Performance Characteristics

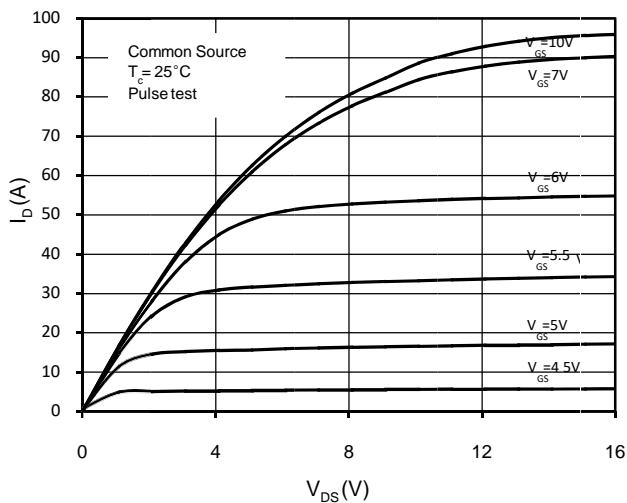


Figure 1. On-Region Characteristics

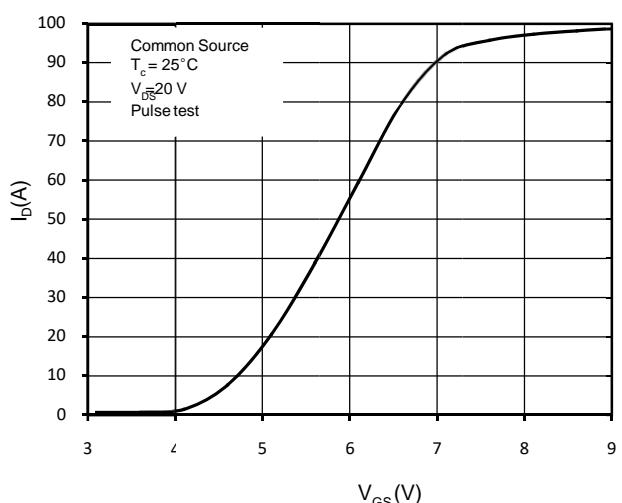


Figure 2. Transfer Characteristics

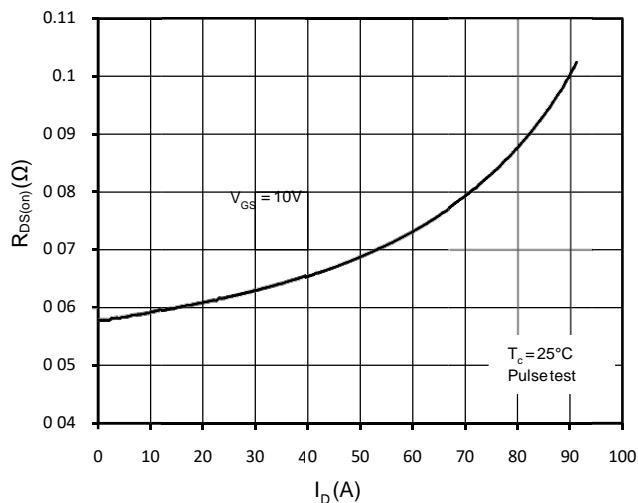


Figure 3. Static Drain-Source On Resistance

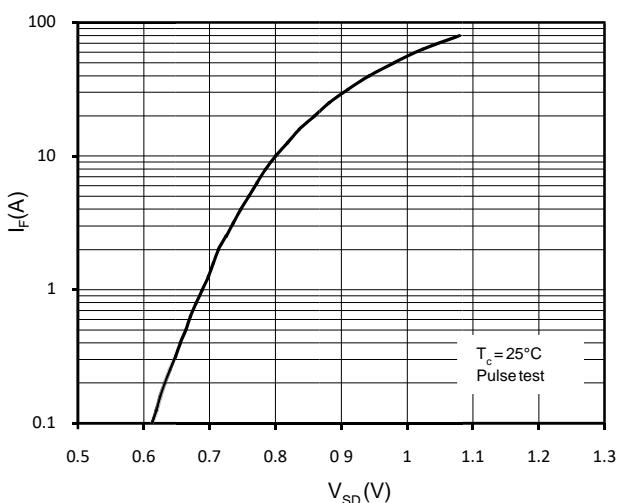


Figure 4. Body-Diode Forward Characteristics

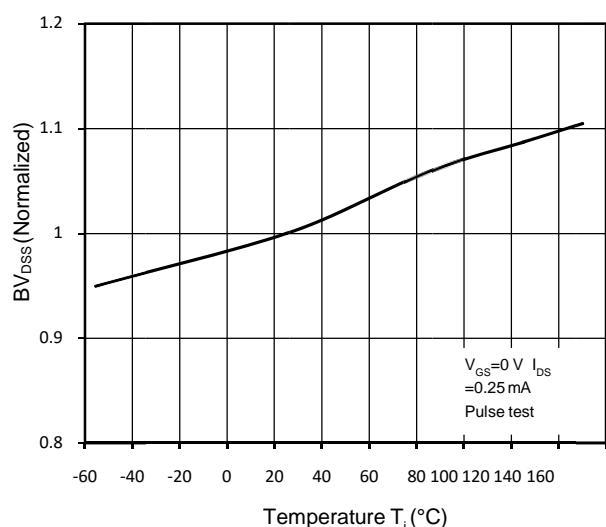


Figure 5. Normalized BV_{DS} vs. Temperature

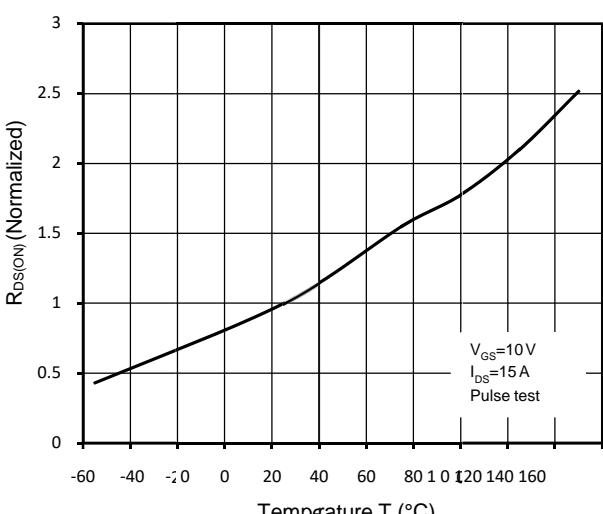


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

Typical Performance Characteristics(Con.)

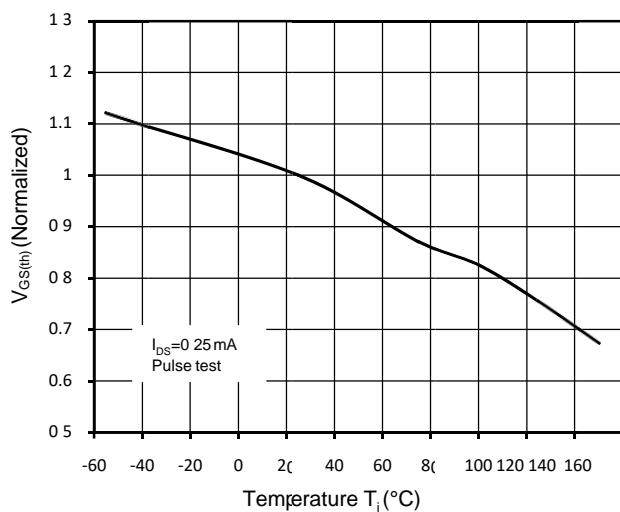


Figure 7. Threshold Voltage vs. Temperature

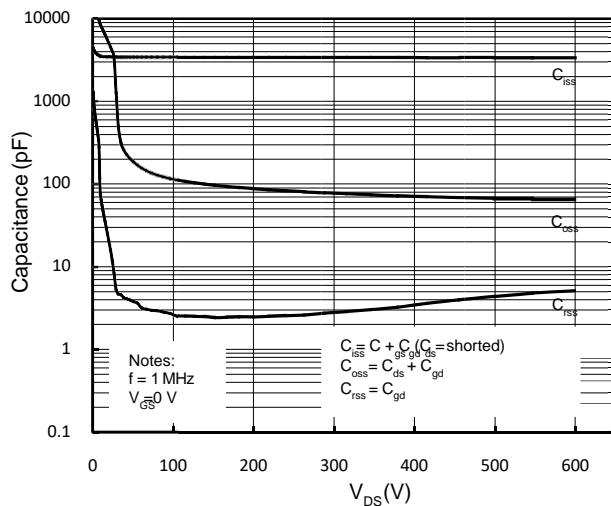


Figure 8. Capacitance Characteristics

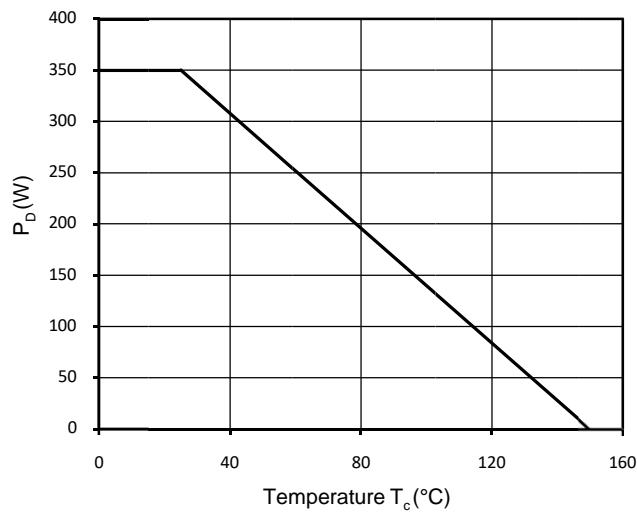


Figure 9. Power Dissipation

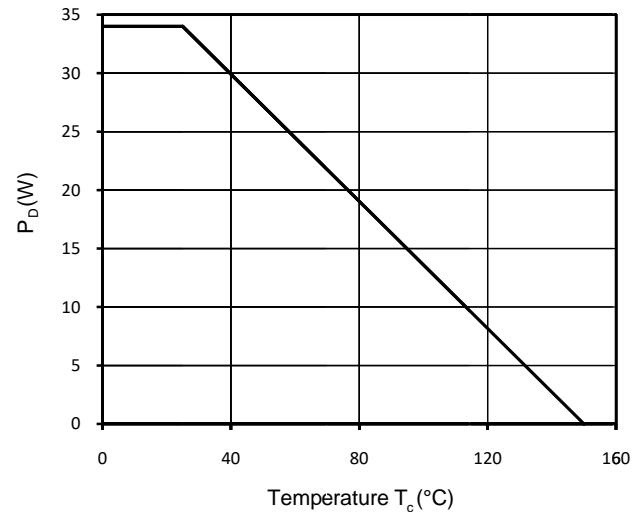


Figure 10. Power Dissipation (TO-220F)

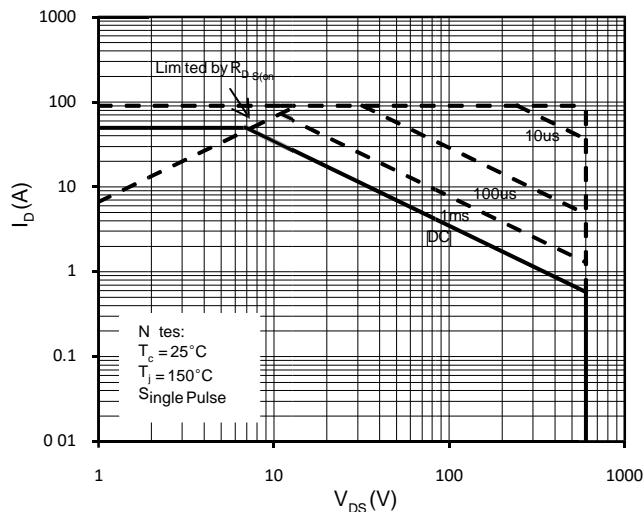


Figure 11. Maximum Safe Operating Area

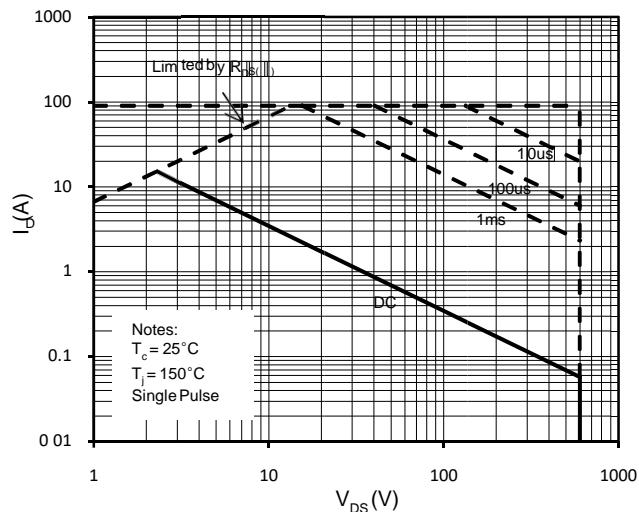


Figure 12. Maximum Safe Operating Area(TO-220F)

Typical Performance Characteristics(Con.)

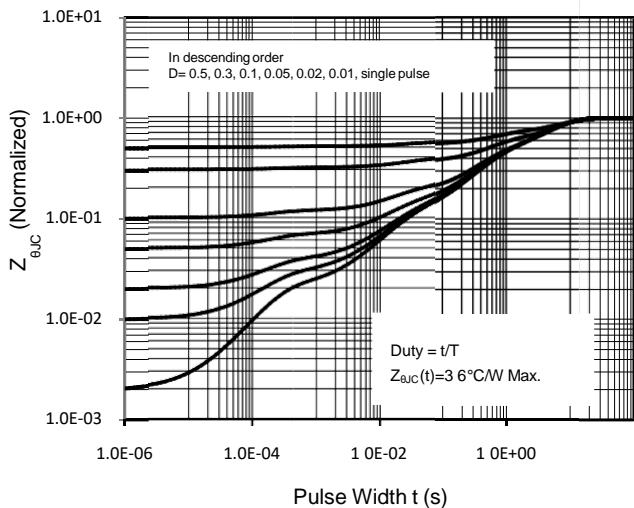


Figure 13. Transient Thermal Response Curve (TO-220F)

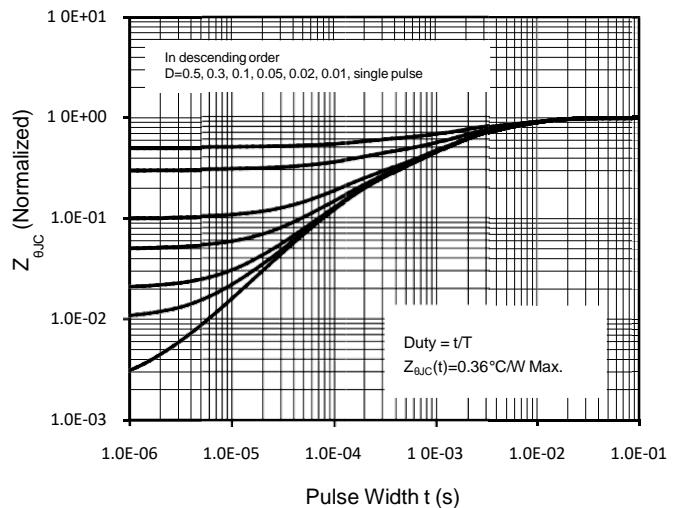


Figure 14. Transient Thermal Response Curve

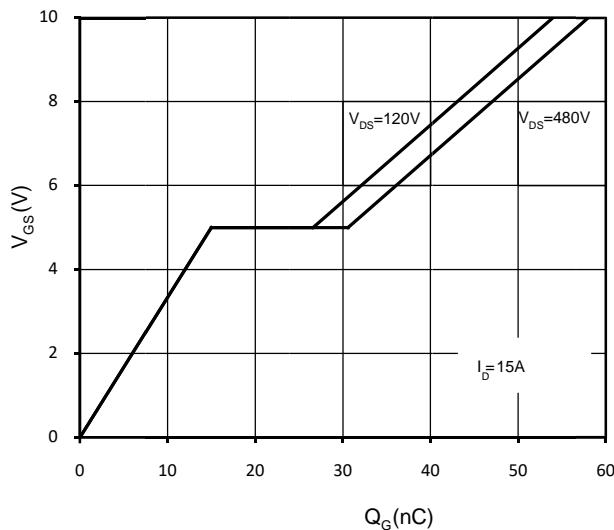
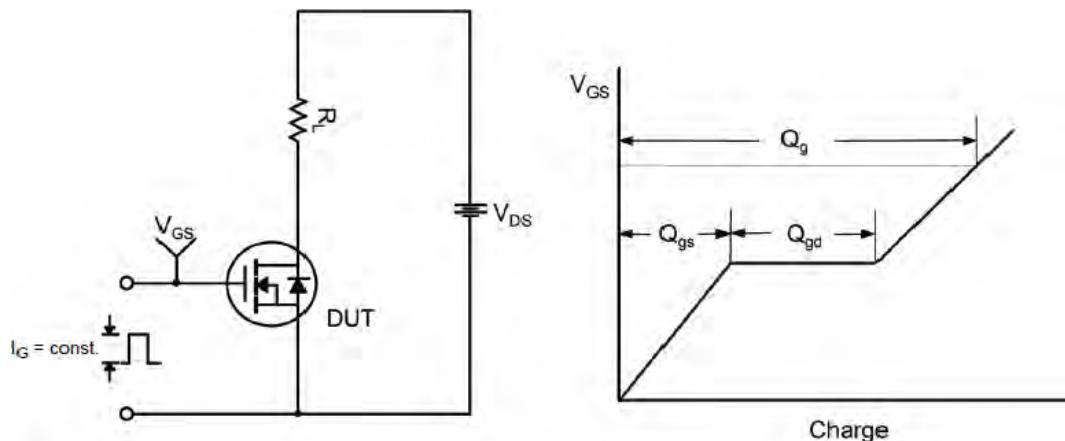
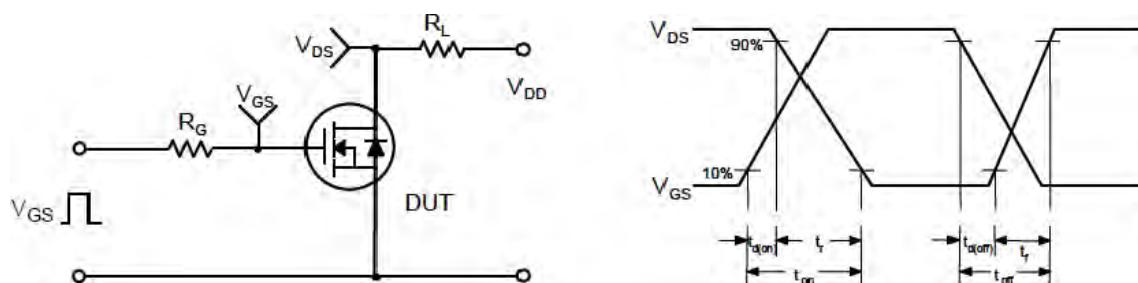
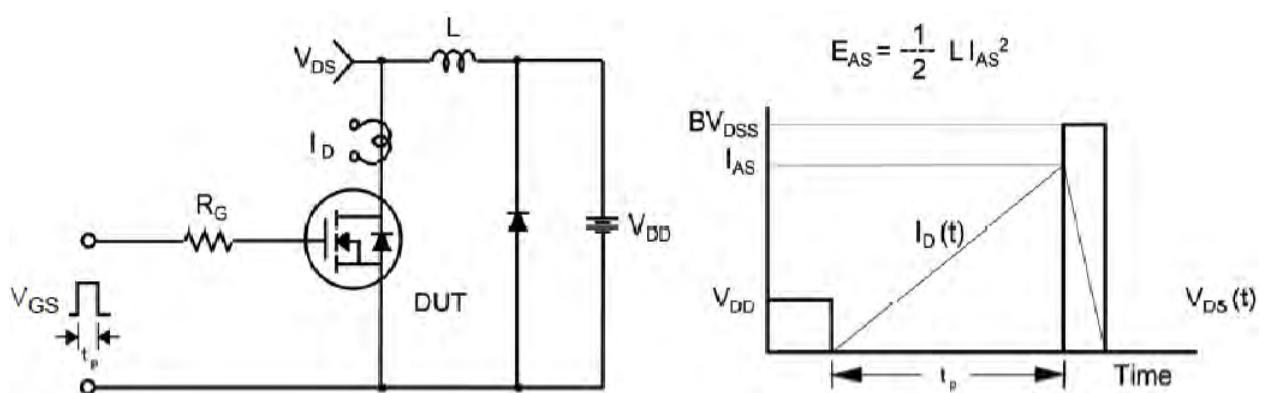
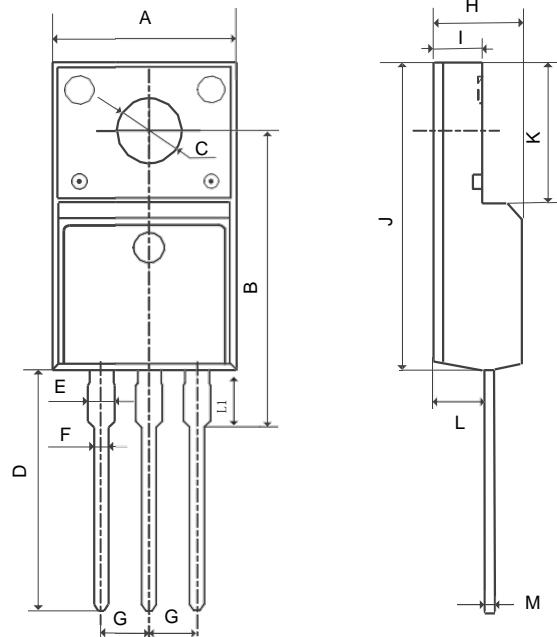


Figure 15. Gate Charge Characteristics

Gate Charge Test Circuit & Waveform

Switching Test Circuit & Waveforms

Unclamped Inductive Switching Test Circuit & Waveforms


Mechanical Dimensions for TO-220F**COMMON DIMENSIONS**

SYMBOL	MM	
	MIN	MAX
A	9.96	10.36
B	15.10	16.10
C	3.03	3.38
D	12.64	13.28
E	1.18	1.58
F	0.70	0.95
G	2.54REF	
H	4.50	4.90
I	2.34	2.74
J	15.57	16.17
K	6.70REF	
L	2.56	2.96
M	0.40	0.65
L1	2.85	3.45